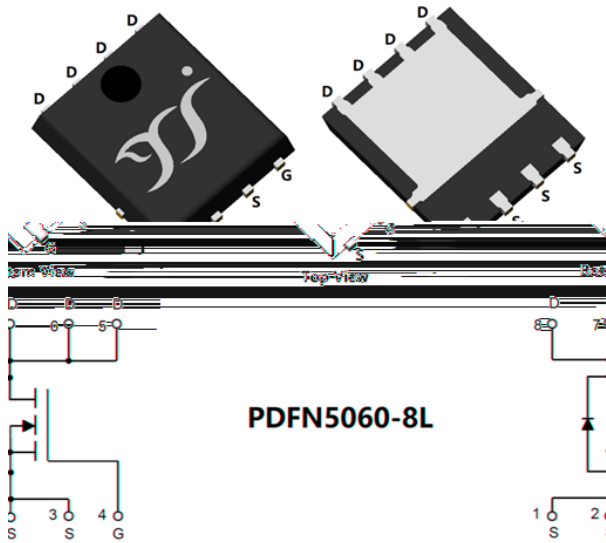


N-Channel Enhancement Mode Field Effect Transistor



PDFN5060-8L

Product Summary

V_{DS}	80V
I_D	100A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	4.5mohm
100% EAS Tested	
100% V_{DS} Tested	

General Description

- Split gate trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- Battery protection
- Load switch
- Uninterruptible power supply

Absolute Maximum Ratings ($T_A=25$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	80	V
Gate-source Voltage		V_{GS}	20	V
Drain Current	$T_C=25$	I_D	100	A
	$T_C=100$		63	
Pulsed Drain Current ^A		I_{DM}	400	A
Avalanche energy ^B		EAS	600	mJ
Total Power Dissipation ^C	$T_C=25$	P_D	152	W
	$T_C=100$		61	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 +150	

Thermal resistance

Parameter		Symbol	Limit	Units
Thermal Resistance Junction-to-Ambient ^D	t 10S	$R_{\theta J-A}$	22.3	/W
Thermal Resistance Junction-to-Ambient ^D	Steady-State		40.7	
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta J-C}$	0.819	

Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJG100G08A	F1	YJG100G08A	5000	10000	100000	13 reel



YJG100G08A

Electrical Characteristics (T_J=25 unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250 ;	80	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V, V _{GS} =0V	-	-	1	;
Gate-Body Leakage Current	I _{GSS}	V _{GS} = 20V, V _{DS} =0V	-	-	100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250 ;	2.0	3.0	4.0	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A	-	3.6	4.5	m
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V	-	0.8	1.2	V
Maximum Body-Diode Continuous Current	I _S		-	-	100	A
Gate resistance	R _G	f=1MHz	-	2	-	
Transconductance	G _{fs}	V _{DS} =10V, I _D =50A		71.5		S
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =40V, V _{GS} =0V, f=1MHZ	-	5666	-	pF
Output Capacitance	C _{oss}		-	860	-	
Reverse Transfer Capacitance	C _{rss}		-	7.5	-	
Switching Parameters						
Total Gate Charge	Q _g	V _{DS} =40V , V _{GS} =10V , I _D =50A	-	73	-	nC
Gate-Source Charge	Q _{gs}		-	25	-	
Gate-Drain Charge	Q _{gd}		-	12	-	
Reverse Recovery Charge	Q _{rr}	I _F =50A , di/dt=100A/us	-	50	-	
Reverse Recovery Time	t _{rr}		-	44	-	
Turn-on Delay Time	t _{d(on)}	P M7. P & PAM7+ P & LA7- & ID=50A	-	27	-	ns
Turn-on Rise Time	t _r		-	32	-	
Turn-off Delay Time	t _{d(off)}		-	54	-	
Turn-off fall Time	t _f		-	17	-	

A. Repetitive rating; pulse width limited by max. junction temperature.

B. T_J=25 , V_{DD}=50V, V_{GS}=10V, L=3mH I_{as}=20A.

C. P_d is based on max. junction temperature, using junction-case thermal resistance.

D. The value of R_D is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25 C.



■ Typical Performance Characteristics

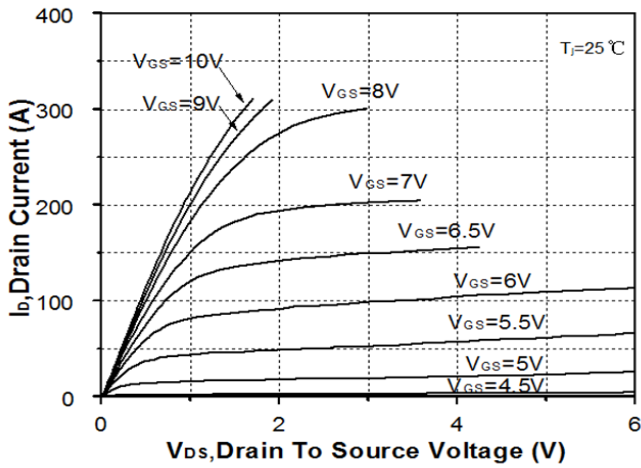


Figure1. Output Characteristics

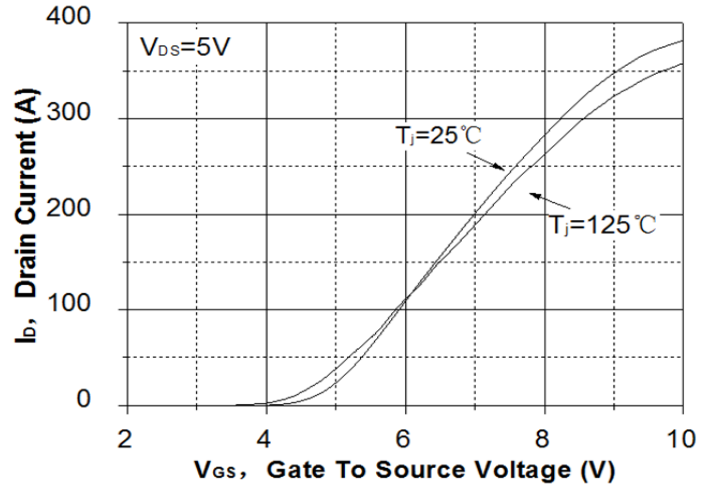


Figure2. Transfer Characteristics

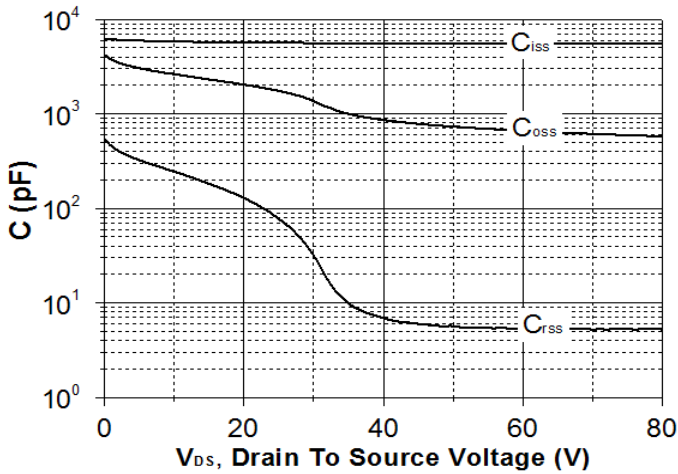


Figure3. Capacitance Characteristics

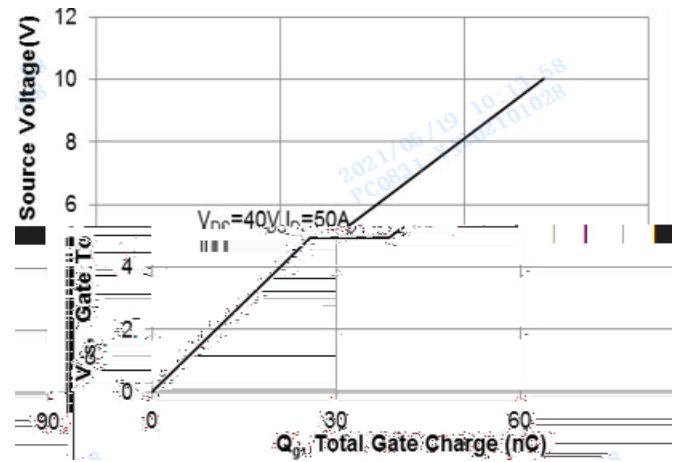


Figure4. Gate Charge

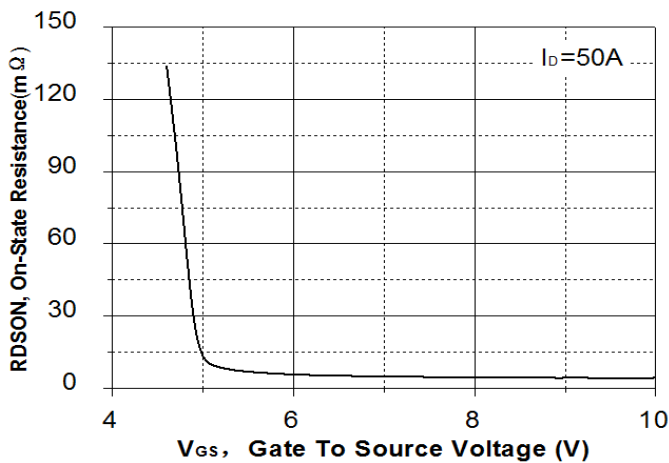


Figure5. On-Resistance vs. Gate to Source Voltage

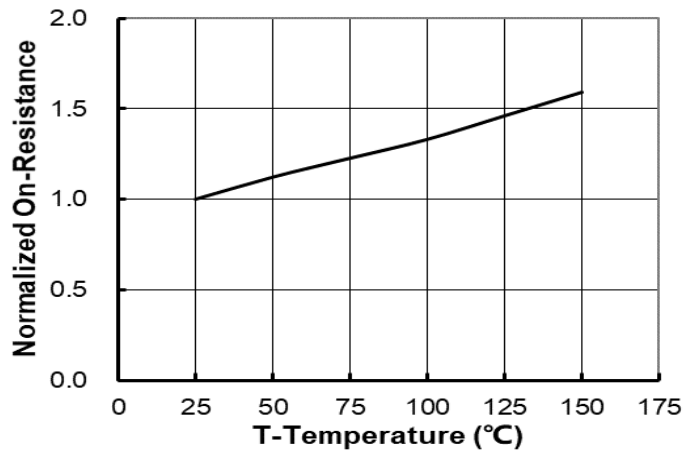


Figure6. Normalized On-Resistance



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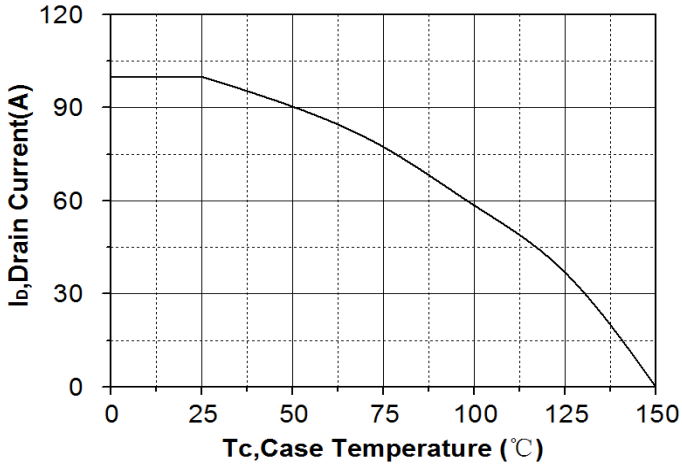


Figure7. Drain current

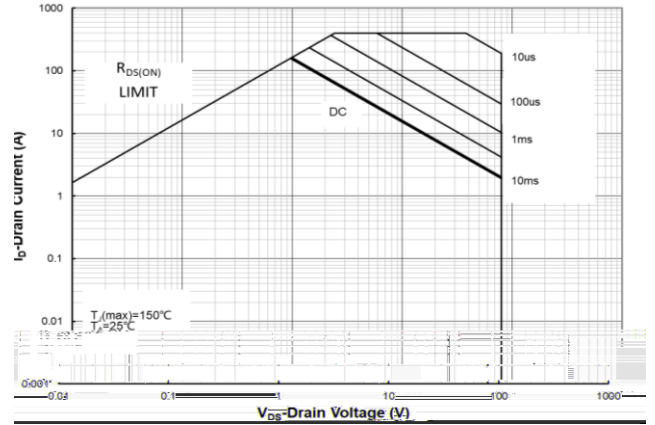


Figure8. Safe Operation Area

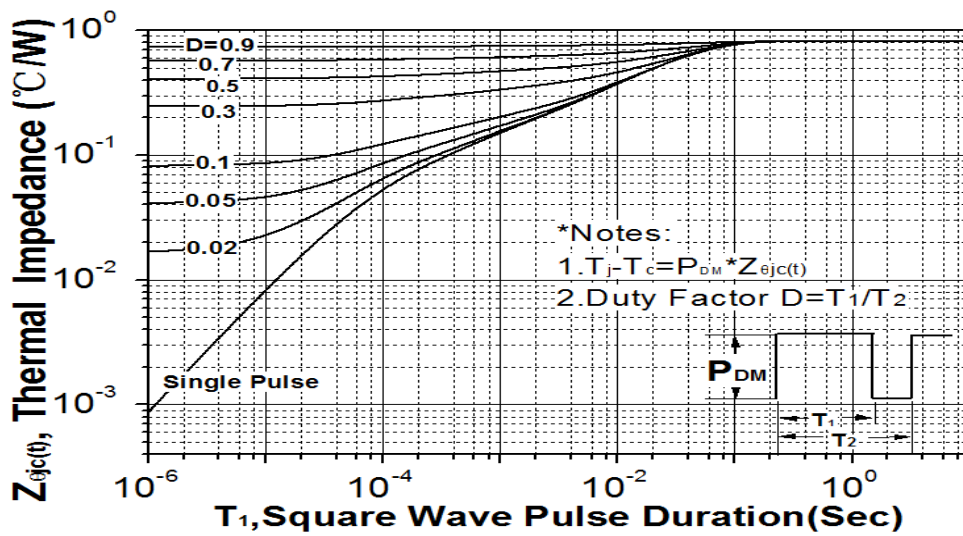
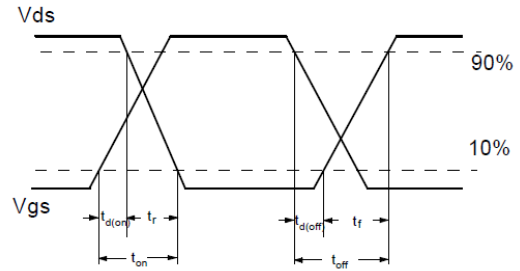
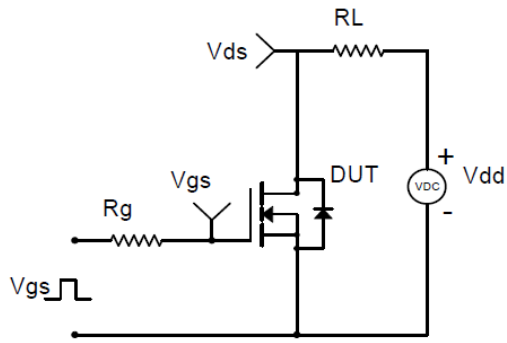
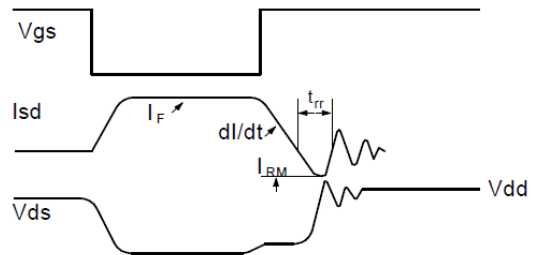
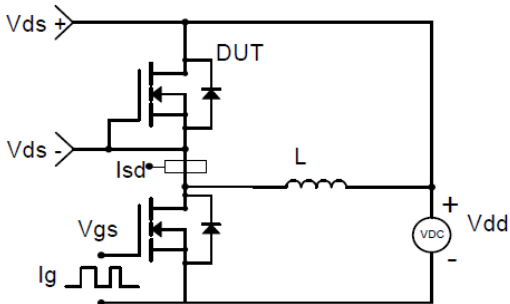


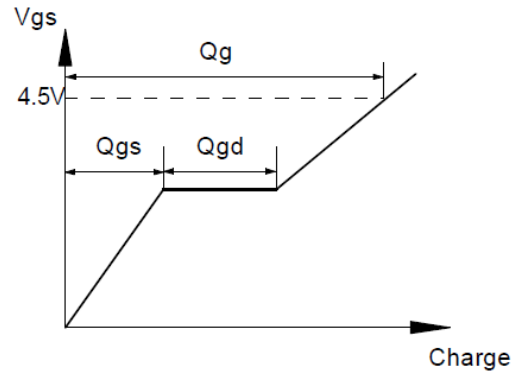
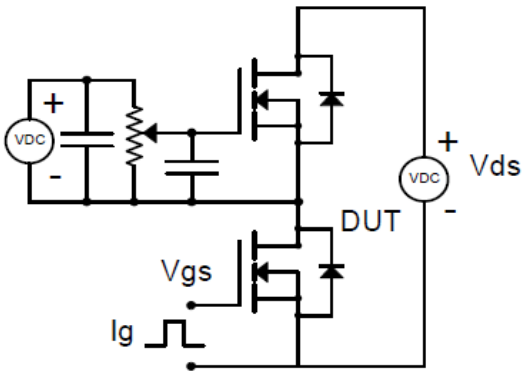
Figure9. Normalized Maximum Transient thermal impedance



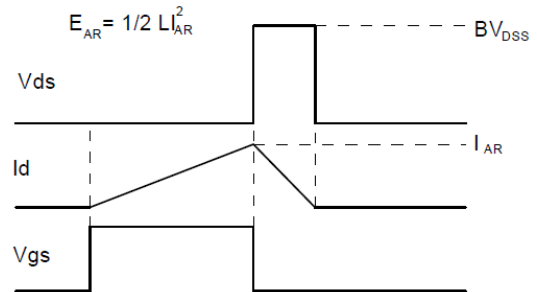
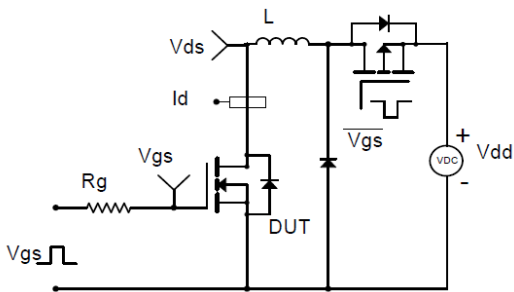
Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Gate Charge Test Circuit & Waveform

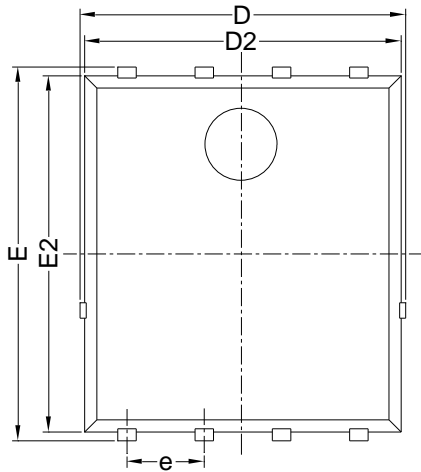


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

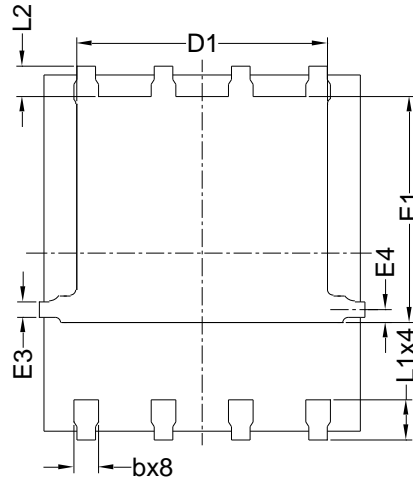


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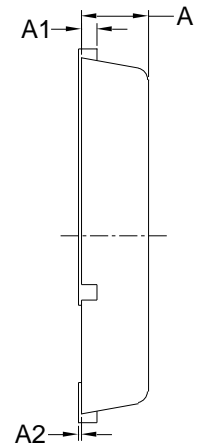
PDFN5060-8L-B-1.1MM Package information



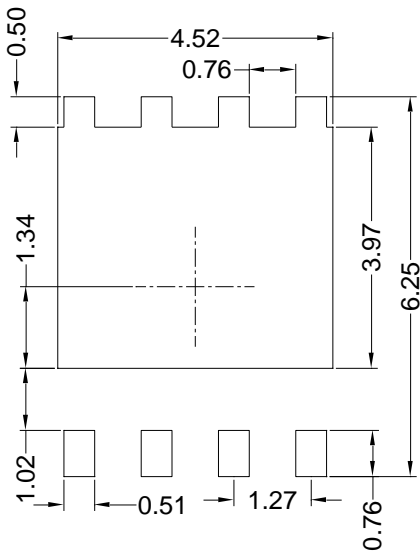
Top View



Bottom View



Side View



Suggested Solder Pad Layout
Top View

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.15	5.35	5.55
E	5.95	6.15	6.35
A	1.00	1.10	1.20
A1	0.254 BSC		
A2			0.10
D1	3.92	4.12	4.32
E1	3.52	3.72	3.92
D2	5.00	5.20	5.40
E2	5.66	5.86	6.06
E3	0.254 REF		
E4	0.21 REF		
L1	0.56	0.66	0.76
L2	0.50 BSC		
b	0.31	0.41	0.51
e	1.27 BSC		

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.10 mm.
3. The pad layout is for reference purposes only.



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